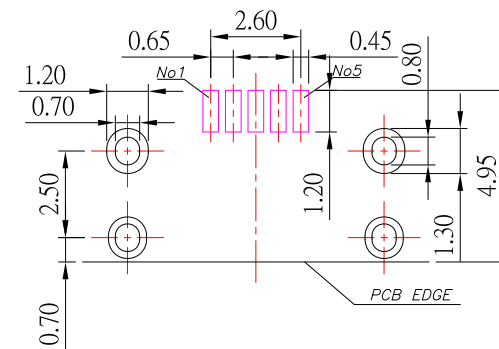
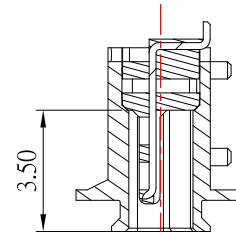
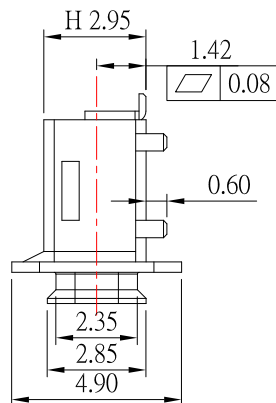
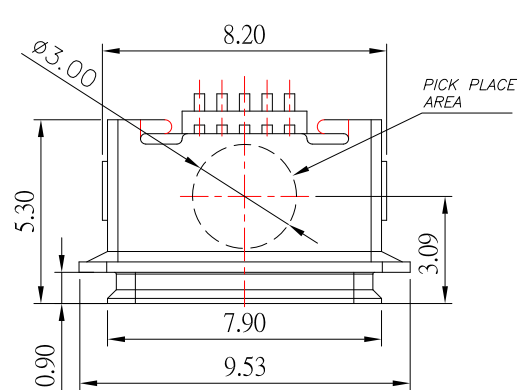
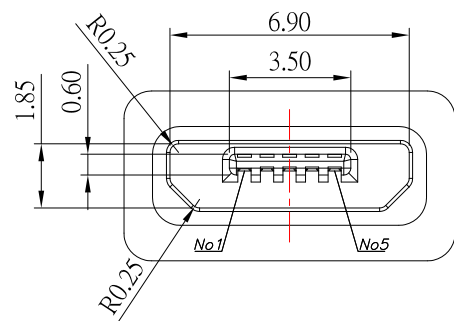


IPX7



P.C.B LAYOUT MOUNTING PATTERN



MRUSB-5B-WP10-x-S382

鍍層厚度:

Blank : 1u"
2 : 15u"
3 : 30u"

NOTES:

MATERIAL:

1.1 HOUSING: HIGH-TEMP

1.2 CONTACT: COPPER ALLOY

1.3 SHELL: SUS

FINISH:

2.1 CONTACT: PLATED GOLD IN MATING AREA ;
GOLD PLATED ON SOLDER BALLS ;
NICKEL UNDER PLATED OVERALL

2.2 SHELL: NICKEL UNDER PLATED SURFACE LAYER

3.SPECIFICATION:

3.1 RATING: 1.8A(PIN1&5) , 0.5A(PIN2&3&4)

3.2 DIELECTRIC WITHSTANDING VOLTAGE: 100 VAC

3.3 CONTACT RESISTANCE: 30 mΩ MAX.

3.4 INSULATION RESISTANCE: 1000 MΩ MIN.



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CONTACT TECHNOLOGY CORP.

TOLERANCE UNLESS
OTHERWISE STATED:

Up to 5 ±0.2
Above 5 ~ 15 ±0.3
Above 15 ~ 30 ±0.4
Above 30 ~ 50 ±0.5
Angle ±0.3°

3RD.
ANGEL'S



UNITS

MM

DRAWN BY: Jack Lu
CHECKED BY: Jacky Chen
APPROVED BY: Tony Kao

DATE: 09/09/20
DATE: 09/09/20
DATE: 09/09/20

MAT'L
FINISH
SCALE
SHEET NO.

TITLE
MODLE
DWG NO.
PART NO.

CONNECTOR
MICRO USB 5PF B TYPE H 2.95
防水型 IPX7
MRUSB-5B-WP10-x-S382
MRUSB-5B-WP10-x-S382

SIZE
A4
VER
R3

ITEM NO.	DESCRIPTION	DRAWN	DATE
3	新增O-RING料號	Jack	090920
2	更新圖面	Jack	090820
1	更新圖面	Jack	051418

IPX7



機殼面板對密封圈
為縮量0.40Min

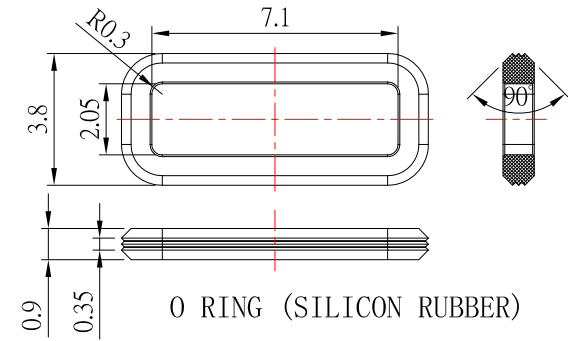
機殼面板對密封圈為縮量0.30Min
(建議壓縮量為密封圈直徑大小40~50%)

1.3 REF

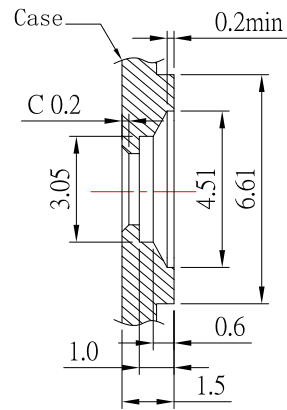
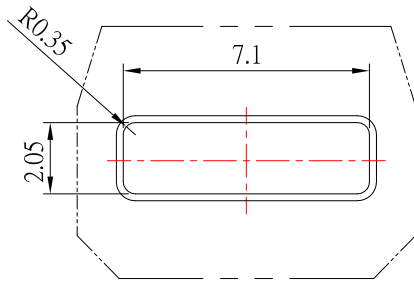
0.6

PCBA

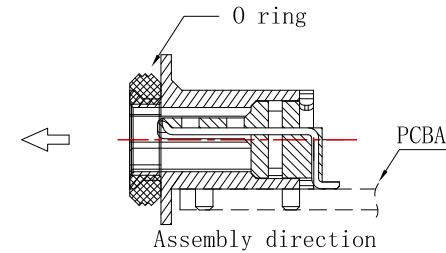
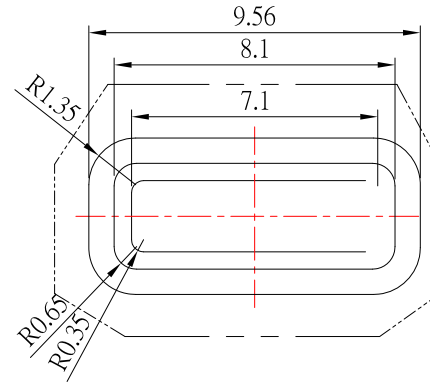
COMPRESSION RATIO TO BE 40%-50%



P/N:PT-ORING-5-S382



RECOMMENDED OPEN DIMENSION OF CASE



CONTACT

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TOLERANCE UNLESS
OTHERWISE STATED:

Up to 5 ±0.2
Above 5 ~ 15 ±0.3
Above 15 ~ 30 ±0.4
Above 30 ~ 50 ±0.5
Angle ±0.3°

3RD.
ANGEL'S



UNITS

MM

DRAWN BY: Jack Lu
CHECKED BY: Jacky Chen
APPROVED BY: Tony Kao

DATE: 09/09/20
DATE: 09/09/20
DATE: 09/09/20

MAT'L
FINISH
SCALE: 1 : 1
SHEET NO. 2 of 2

TITLE
MODLE
DWG NO.
PART NO.

CONNECTOR
MICRO USB 5PF B TYPE H 2.95
防水型 IPX7
MRUSB-5B-WP10-x-S382
MRUSB-5B-WP10-x-S382

SIZE: A4
VER: R3